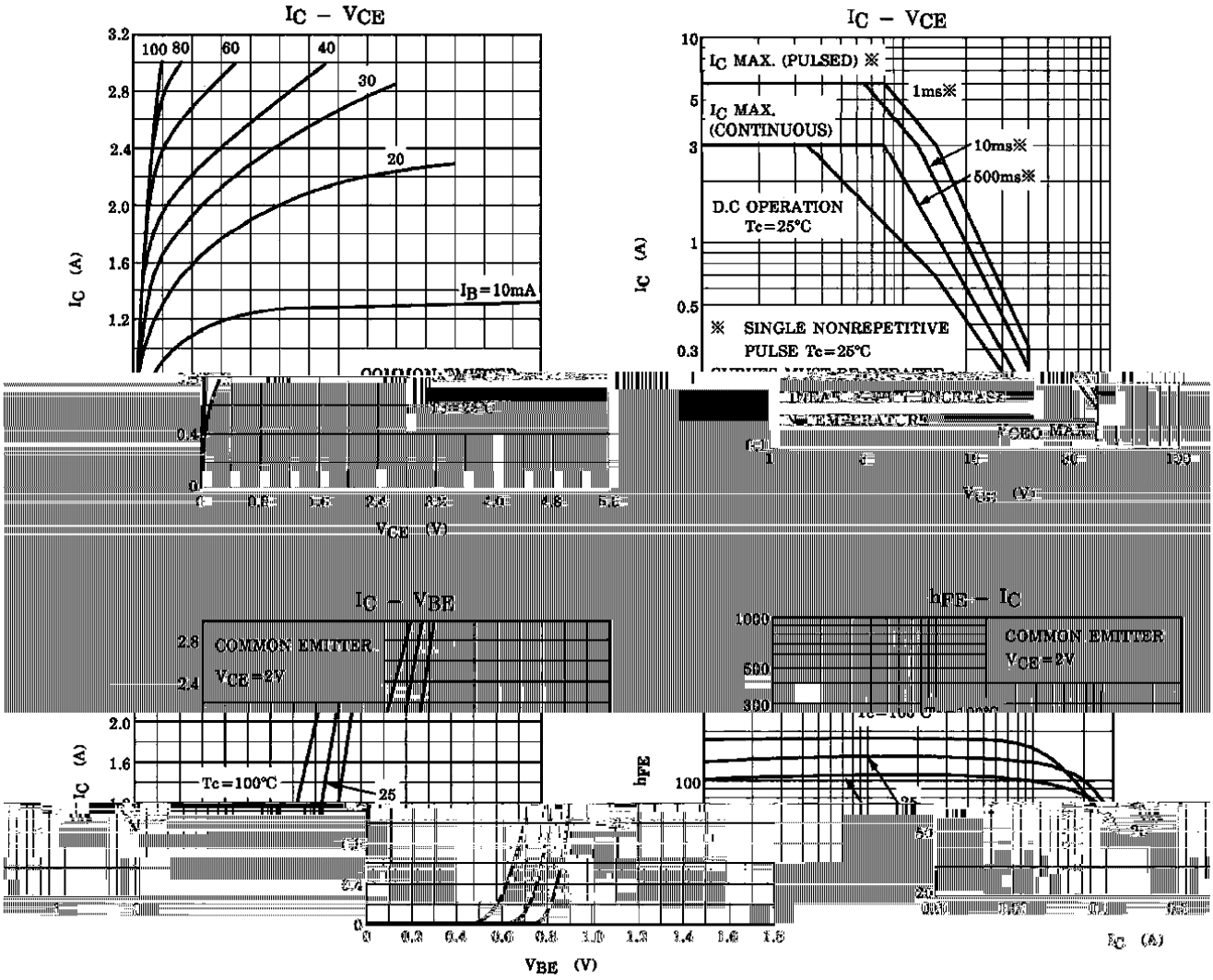
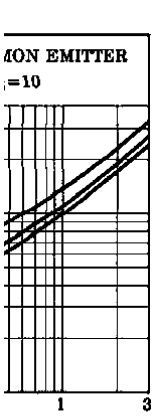
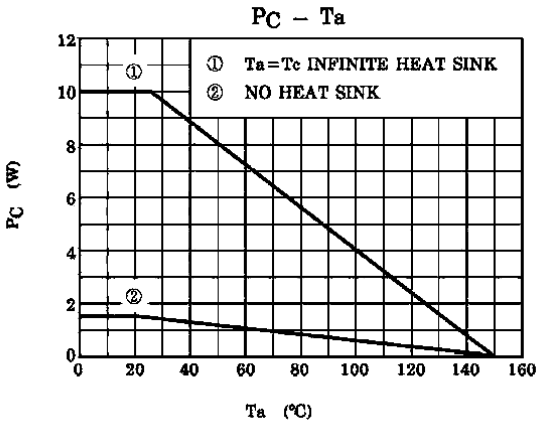
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	40	V
Collector to Emitter Voltage	V_{CEO}	40	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current - Continuous	I_C	3.0	A
Base Current – Continuous	I_B	1.0	A
Collector Power Dissipation	P_C	1.5	W
Collector Power Dissipation	P_C(Tc=25)	10	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

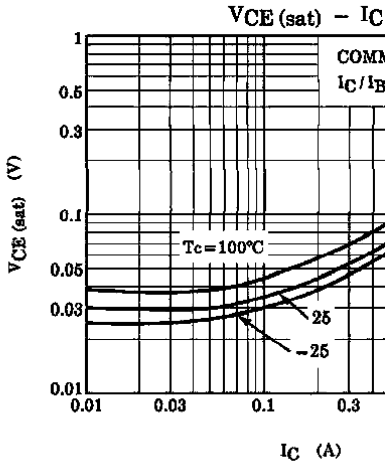
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown Voltage	V_{CEO}	I_C=10mA I_B=0	40			V
Collector Cut-Off Current	I_{CBO}	V_{CB}=40V I_E=0			0.1	μA
Emitter Cut-Off Current	I_{EBO}	V_{EB}=5.0V I_C=0			0.1	μA
DC Current Gain	$h_{FE(1)}$	V_{CE}=2.0V I_C=0.5A	80		400	
	$h_{FE(2)}$	V_{CE}=2.0V I_C=2.5A	25			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	I_C=2.0A I_B=0.2A			0.8	V
Base to Emitter Voltage	V_{BE}	V_{CE}=2.0V I_C=0.5A			1.0	V
Transition Frequency	f_T	V_{CE}=2.0V I_C=0.5A		100		MHz
Collector output capacitance	C_{ob}	V_{CB}=10V I_E=0 f=1.0MHz		35		pF

/ Electrical Characteristic Curve



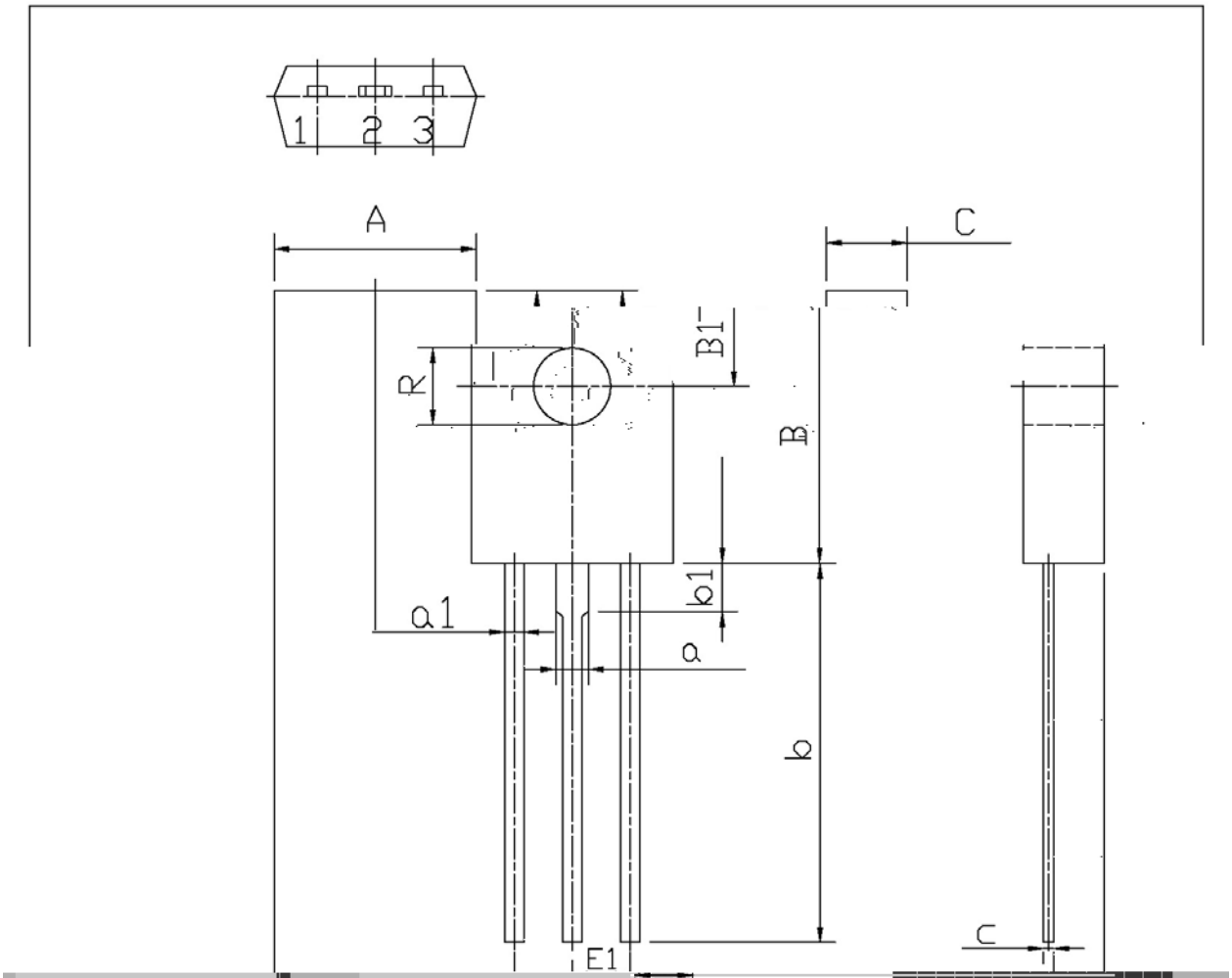






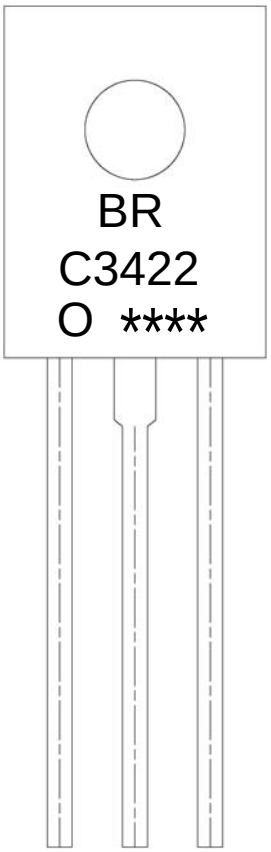
/ Package Dimensions

TO-126F 单位：mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	7.8	8.2	a1	0.66	0.86
B	10.8	11.2	E	4.4	4.8
B1	3.8	4.2	C	3.1	3.3
R	2.95	3.15	C1	1.9	2.1
b	14	16	r	0.3	0.6
e	1.27		b1	1.9	
E1	2.1	2.5			

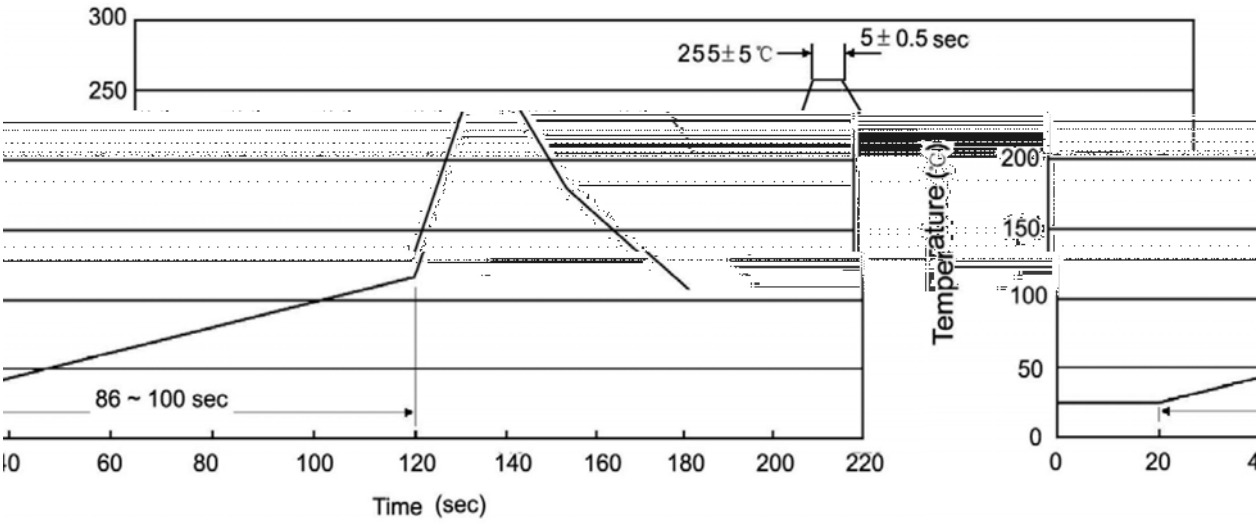
/ Marking Instructions



Note:

BR:	Company Code
C3422:	Product Type.
O:	h_{FE} Classifications Symbol
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



		Note:
1	25 150 60 90sec;	1.Preheating:25~150 , Time:60~90sec.
2	255 5 5 0.5sec;	2.Peak Temp.:255 5 , Duration:5 0.5sec.
3	2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270 5	10 1 sec.	Temp.:270±5